

- L1: (3573) (257/700,703,705,707,782).CCLS.
- L2: (749) (438/125).CCLS.
- L3: (583) (219/121.71).CCLS.
- L5: (12) 2 and (laser near5 weld\$3)
- L6: (13) 3 and (laser near5 weld\$3)
- L4: (31) 1 and (laser near5 weld\$3)
- Failed
- Saved
- (2874) (257/700,703,705,707).CCLS.
- (683) (438/125).CCLS.
- (527) (219/121.71).CCLS.
- (23178) laser near5 weld\$3
- (11327) ceramic adj layer
- (95992) metal adj layer
- (0) (laser near5 weld\$3) with (ceramic adj layer) w
- (0) (laser near5 weld\$3) same (ceramic adj layer) s
- (24) (laser near5 weld\$3) and (ceramic adj layer) ar
- (4) ((laser near5 weld\$3) and (ceramic adj layer) an
- (11) ((438/125).CCLS.) and (laser near5 weld\$3)
- (10) ((219/121.71).CCLS.) and (laser near5 weld\$3)

USPAT; US-PCPUB; EPO; JPO; DERWENT; IBM; TDB
 ☐ Plurals

Default operator:
☒ Highlight all hit terms initially

	U	I	Document ID	Issue Date	Pages	Title	Current	Cur Re	Inventor	S	C	P	2	3
2	□	□	US 20030178718 A1	20030925	8	Hermetically enhanced pl	257/701	257/	Ehly, Jonathan P. et	□	□	□	□	□
3	□	□	US 6632028 B1	20031014	12	Apparatus and method fo	385/88	257/	Yang, Renyi et al.	□	□	□	□	□
4	□	□	US 6507114 B2	20030114	12	BOC semiconductor pac	257/738	257/	Hui, Chong Chin et	□	□	□	□	□
5	□	□	US 6404042 B1	20020611	16	Subcarrier and semicond	257/678	257/	Sone, Minoru et al.	□	□	□	□	□
6	□	□	US 6316832 B1	20011113	28	Moldless semiconductor	257/747	257/	Tsuzuki, Koji et al.	□	□	□	□	□
7	□	□	US 6166438 A	20001226	20	Ultrathin electronics usin	257/725	257/	Davidson, Howard	□	□	□	□	□